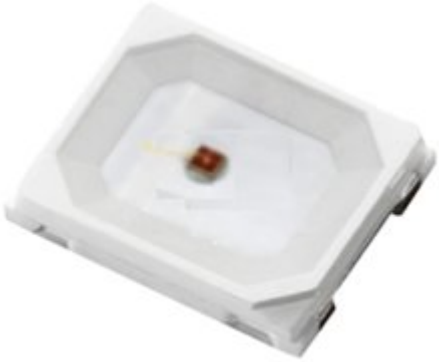
DATASHEET

SMD ▪Low Power LED
EAPL2835YA0



Features

- PLCC-2 package
- Top view Yellow LED
- Wide viewing angle
- Pb-free
- RoHS compliant

Description

The Everlight EAPL2835 package has high efficacy, Low Power consumption, wide viewing angle and a compact form factor. These features make this package an ideal LED for all lighting applications.

Applications

- Decorative and Entertainment Lighting
- Agriculture Lighting
- General use

Device Selection Guide

Chip Materials	Emitted Color	Resin Color
AlGaInP	Orange	Water Clear

Absolute Maximum Ratings ($T_{Soldering}$=25℃)

Parameter	Symbol	Rating	Unit
Forward Current	I_F	20	mA
Peak Forward Current (Duty 1/10 @10ms)	I_{FP}	40	mA
Power Dissipation	P_d	50	mW
Operating Temperature	T_{opr}	-40 ~ +85	℃
Storage Temperature	T_{stg}	-40 ~ +100	℃
Thermal Resistance (Junction / Soldering point)	$R_{th\ J\text{-}S}$	50	℃/W
Junction Temperature	T_j	115	℃
Soldering Temperature	T_{sol}	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

Note:
The products are sensitive to static electricity and must be carefully taken when handling products

Electro-Optical Characteristics ($T_{Soldering}$=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous flux (1)	Ø	0.1	-----	1	lm	I_F=20mA
Forward Voltage	V_F	1.8	-----	2.5	V	I_F=20mA
Viewing Angle	$2\theta_{1/2}$	-----	120	-----	deg	I_F=20mA
Reverse Current	IR	-----	-----	50	μA	V_R =5V

Notes:
1. Tolerance of Radiometric Luminous flux: ±11%.
2. Tolerance of Forward Voltage: ±0.1V.

Bin Range of Radiometric Luminous flux

Bin Code	Min.	Max.	Unit	Condition
D0	0.1	0.5	lm	I_F=20mA
D1	0.5	1.0		

Notes:
Tolerance of Luminous flux : ±11%

Bin Range of Forward Voltage

Group	Bin Code	Min.	Max.	Unit	Condition
1825	25	1.8	1.9	V	I_F=20mA
	26	1.9	2.0		
	27	2.0	2.1		
	28	2.1	2.2		
	29	2.2	2.3		
	30	2.3	2.4		
	31	2.4	2.5		

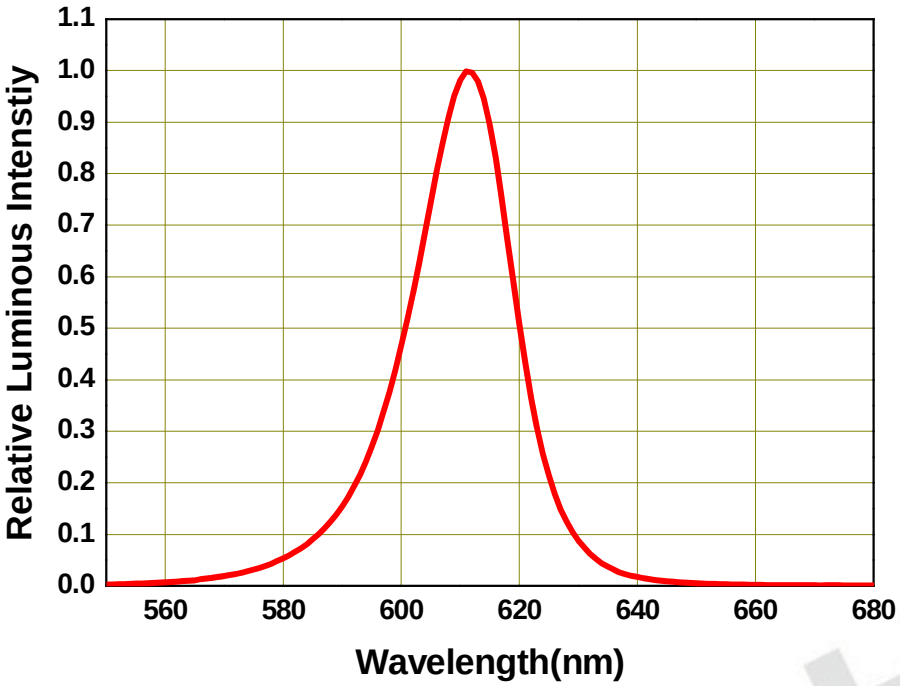
Note:
Tolerance of Forward Voltage: ±0.1V.

Dominant Wavelength Bins

Bin Code	Min.	Max.	Unit	Condition
O51	600	605	nm	I_F=20mA
O52	605	610		
O53	610	615		

Notes:
Dominant / Peak wavelength measurement tolerance: ±1nm.

Spectrum Distribution



Typical Electro-Optical Characteristics Curves

Fig.1 – Forward Voltage Shift vs. Junction Temperature

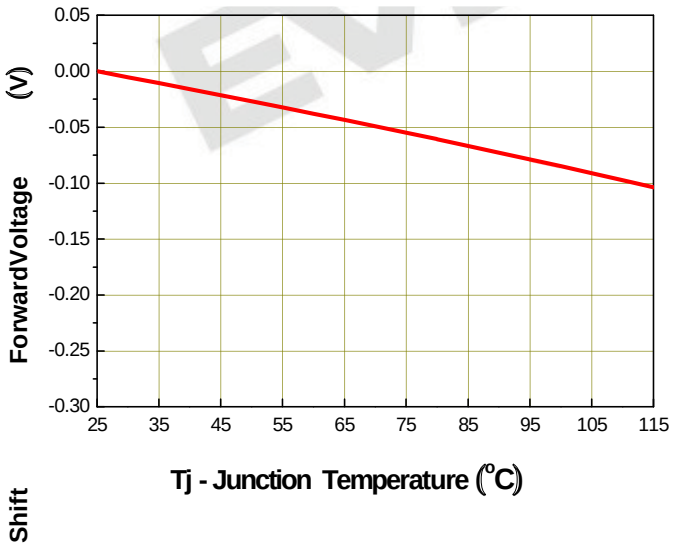
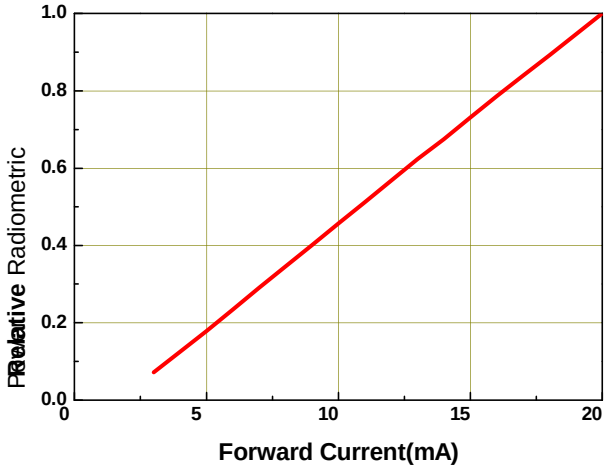


Fig.2 - Relative Radiometric Power vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.3 - Relative Luminous Intensity vs. Junction Temperature

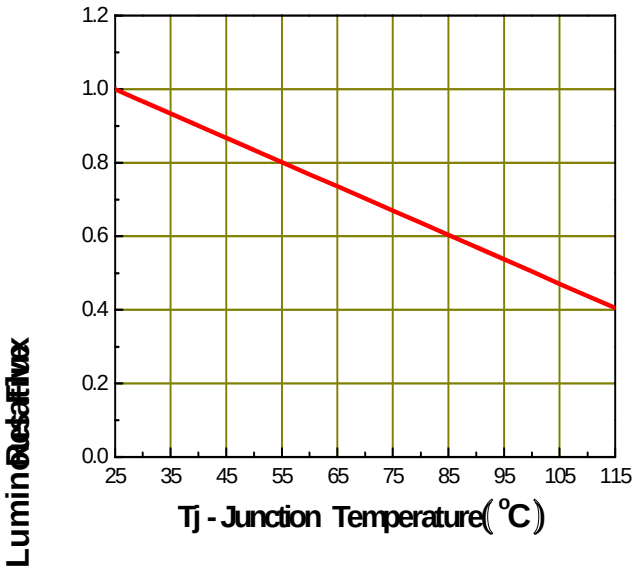


Fig.4 - Forward Current vs. Forward Voltage

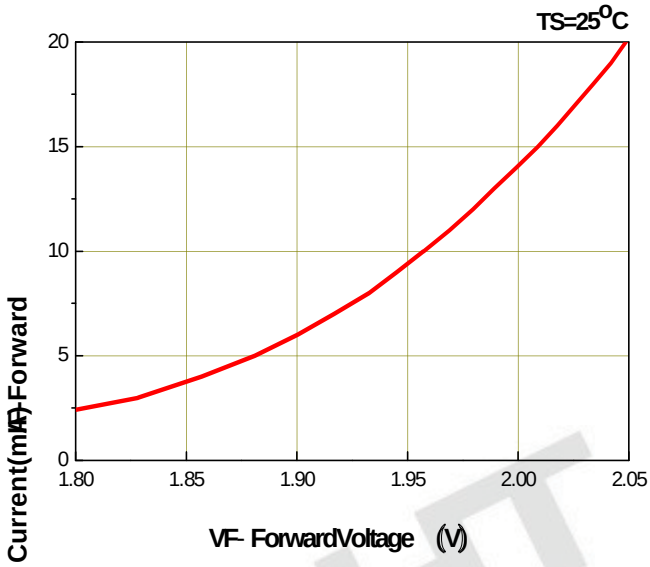


Fig.5 – Max. Driving Forward Current vs. Soldering Temperature

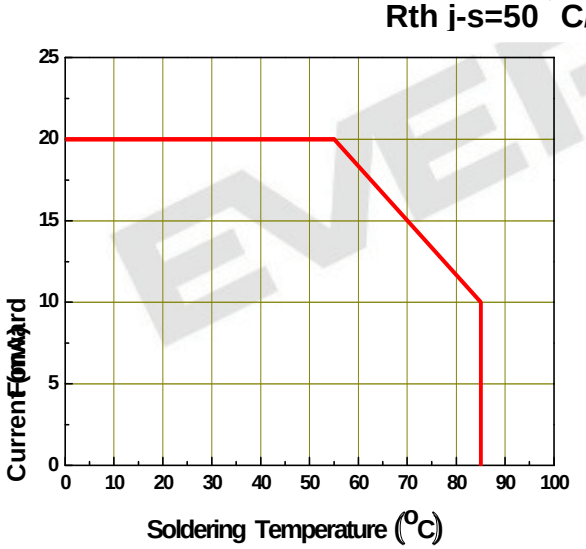
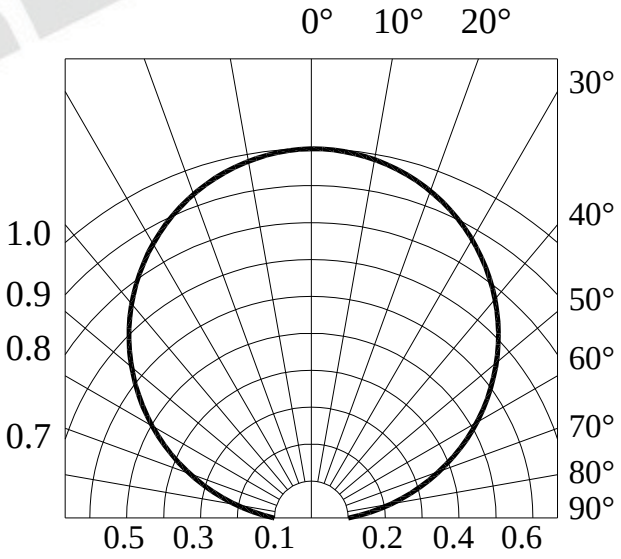
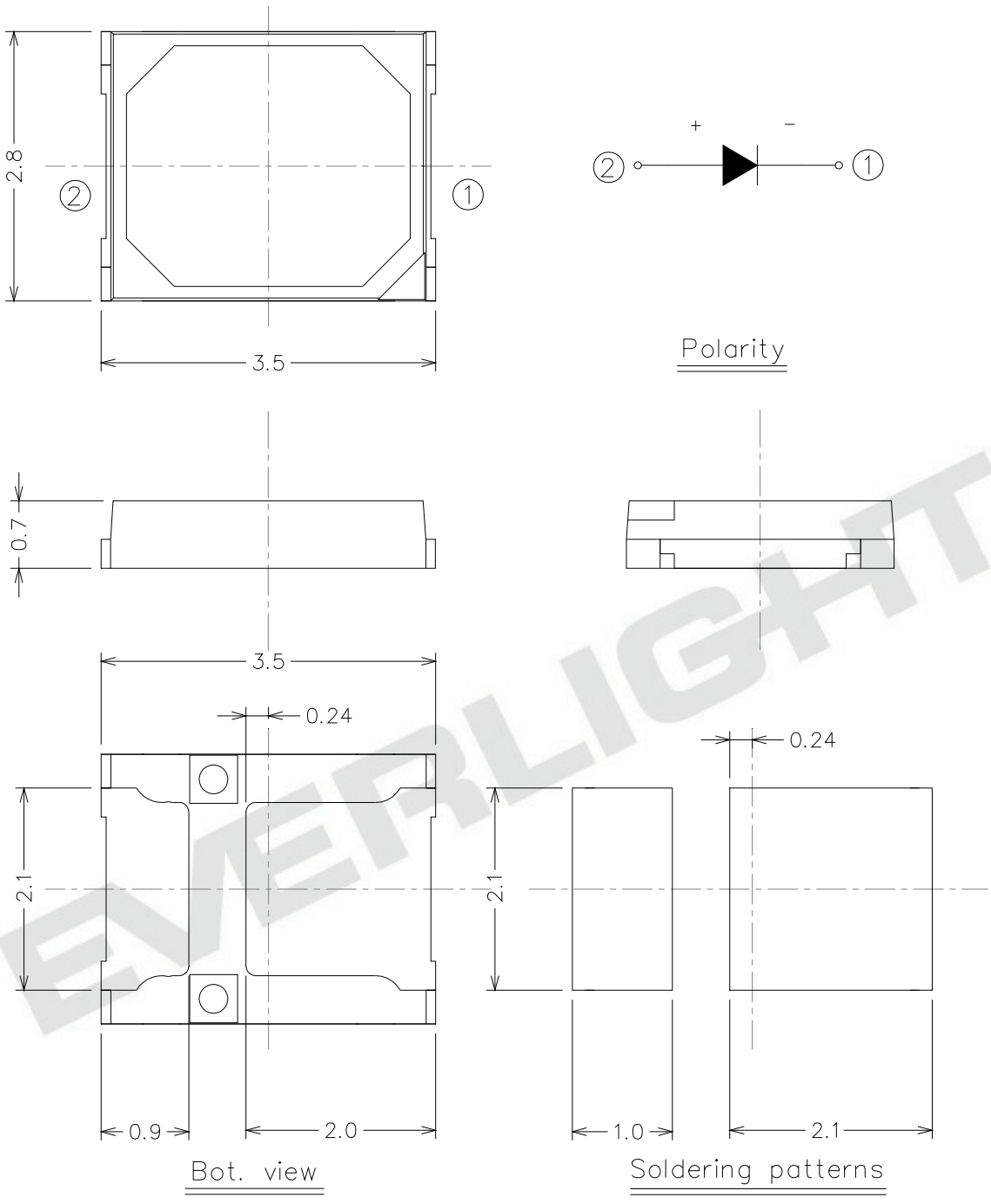


Fig.6 – Radiation Diagram



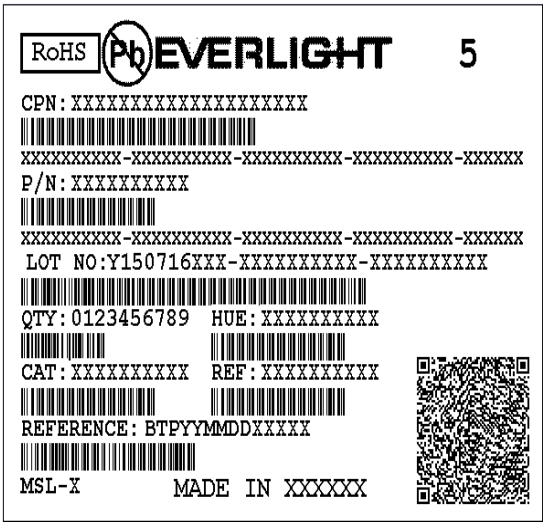
Package Dimension



Note:
Tolerance unless mentioned is ±0.15 mm; Unit = mm

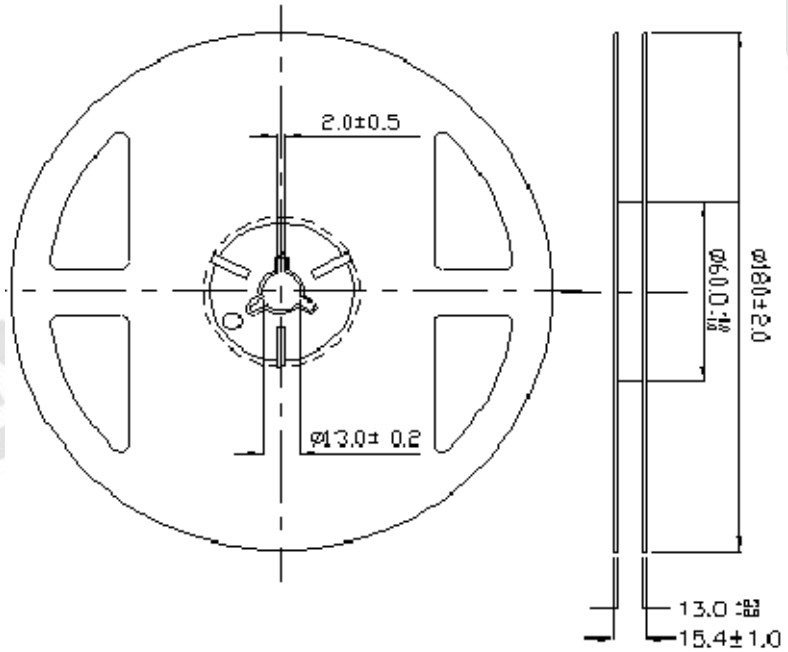
Moisture Resistant Packing Materials

Label Explanation



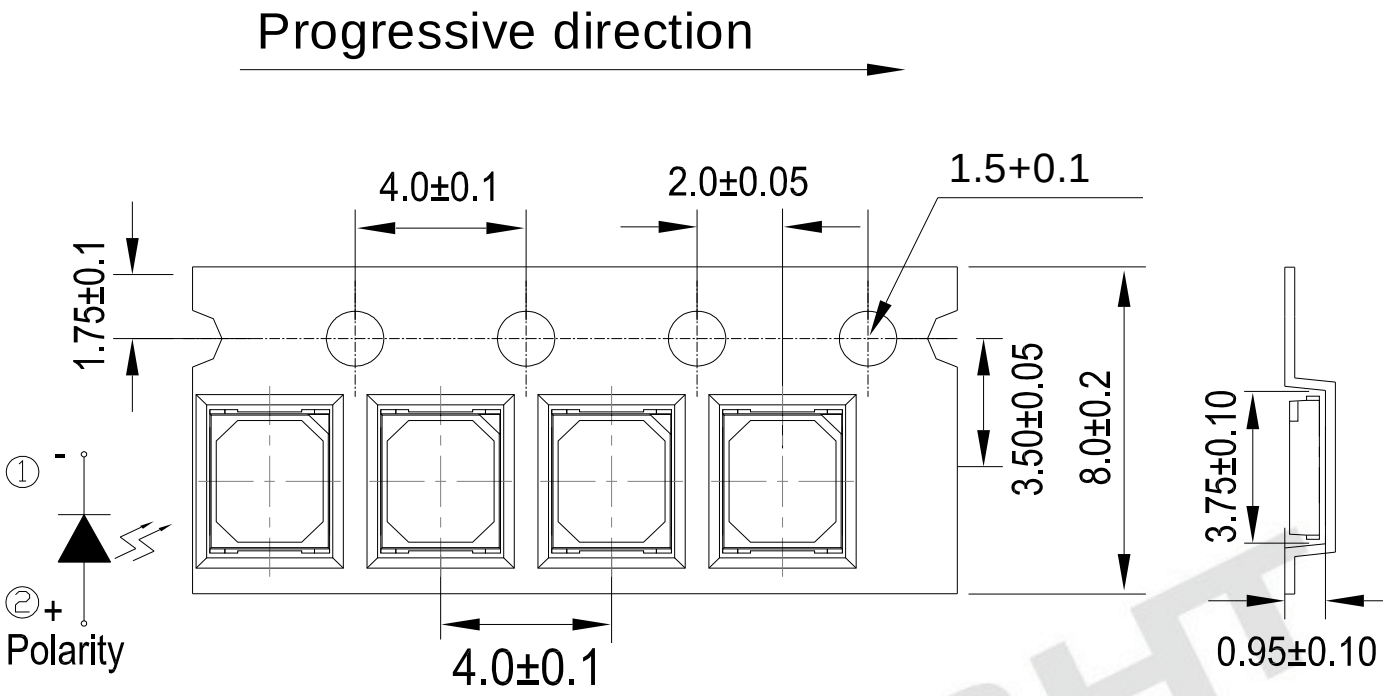
- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number

Reel Dimensions



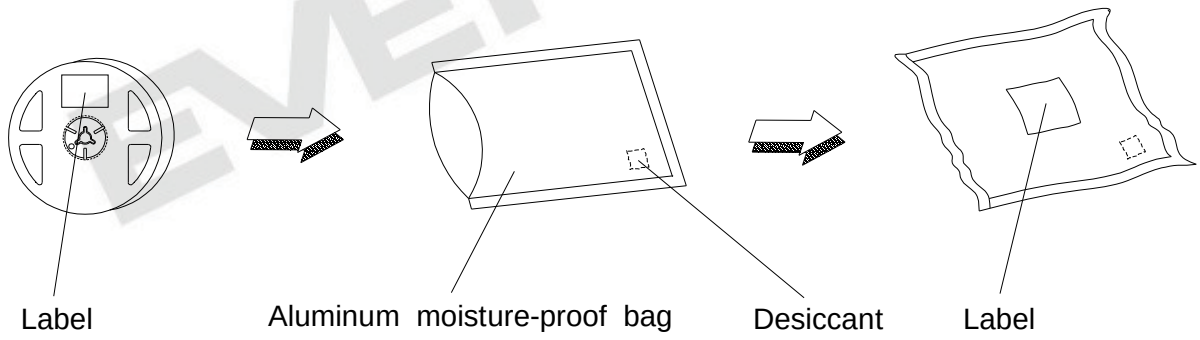
Note:
Tolerances unless mentioned ±0.1mm. Unit = mm

Carrier Tape Dimensions: Loaded Quantity 250/500/1000/2000/3000/4000 pcs. Per Reel



Note:
Tolerance unless mentioned is ±0.1mm; Unit = mm

Moisture Resistant Packing Process



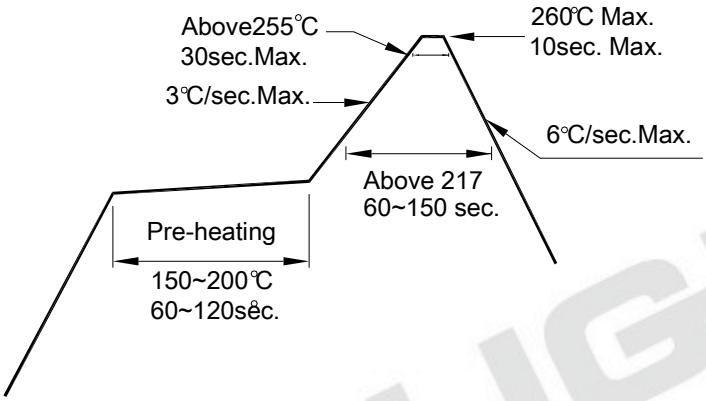
Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.
Confidence level：90%
LTPD：10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260℃/10sec.	6 Min.	22 PCS.	0/1
2	Thermal Shock	H : +100℃ 20min ∫ 10 sec L : -10℃ 20min	200 Cycles	22 PCS.	0/1
3	Temperature Cycle	H : +100℃ 30min ∫ 5 min L : -40℃ 30min	200 Cycles	22 PCS.	0/1
4	High Temperature/Humidity Storage	Ta=85℃,85%RH	1000 Hrs.	22 PCS.	0/1
5	High Temperature/Humidity Operation	Ta=85℃,85%RH, I_F = 10mA	1000 Hrs.	22 PCS.	0/1
6	Low Temperature Storage	Ta=-40℃	1000 Hrs.	22 PCS.	0/1
7	High Temperature Storage	Ta=85℃	1000 Hrs.	22 PCS.	0/1
8	Low Temperature Operation Life	Ta=-40℃, I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
9	High Temperature Operation/ Life#1	Ta=25℃, I_F = 20 mA	1000 Hrs.	22 PCS.	0/1
10	High Temperature Operation/ Life#2	Ta=55℃, I_F =20mA	1000 Hrs.	22 PCS.	0/1
11	High Temperature Operation/ Life#3	Ta=85℃, I_F = 10 mA	1000 Hrs.	22 PCS.	0/1

Precautions for Use

1. Over-current-proof
   Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
2. Storage
   2.1 Do not open moisture proof bag before the products are ready to use.
   2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.
   2.3 After opening the package: The LED's floor life is 168 Hrs under 30℃ or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
   2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
   Baking treatment: 60±5℃ for 24 hours.
3. Soldering Condition
   3.1 Pb-free solder temperature profile



   3.2 Reflow soldering should not be done more than two times.
   3.3 When soldering, do not put stress on the LEDs during heating.
   3.4 After soldering, do not warp the circuit board.
4. Soldering Iron
   Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.
5. Repairing
   Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.